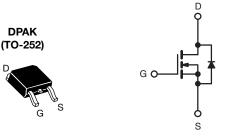
**Vishay Siliconix** 



# **E Series Power MOSFET**

PRODUCT SUMMA	RY	
V <sub>DS</sub> (V) at T <sub>J</sub> max.	550	)
R <sub>DS(on)</sub> max. at 25 °C (Ω)	$V_{GS} = 10 V$	0.380
Q <sub>g</sub> max. (nC)	50	
Q <sub>gs</sub> (nC)	6	
Q <sub>gd</sub> (nC)	10	
Configuration	Sing	le



N-Channel MOSFET

## **FEATURES**

- Low figure-of-merit (FOM) Ron x Qa
- Low input capacitance (Ciss)
- · Reduced switching and conduction losses
- Low gate charge (Q<sub>a</sub>)
- Avalanche energy rated (UIS)
- Material categorization: for definitions of compliance please see <u>www.vishay.com/doc?99912</u>

## **APPLICATIONS**

- Computing
  - PC silver box / ATX power supplies
- Lighting
  - Two stage LED lighting
- Consumer electronics
- Applications using hard switched topologies
  - Power factor correction (PFC)
  - Two switch forward converter
  - Flyback converter
- Switch mode power supplies (SMPS)

# ORDERING INFORMATION Package DPAK (TO-252) Lead (Pb)-free and Halogen-free SiHD12N50E-GE3

PARAMETER			SYMBOL	LIMIT	UNIT
Drain-Source Voltage		V <sub>DS</sub>	500	- V	
Gate-Source Voltage			V <sub>GS</sub>	± 30	v
Continuous Drain Current (T 150 °C)	V <sub>GS</sub> at 10	$V = \frac{T_{C} = 25 \text{ °C}}{T_{C} = 100 \text{ °C}}$	1	10.5	
Continuous Drain Current ( $T_J = 150 \ ^\circ C$ )	V <sub>GS</sub> at 10	v T <sub>C</sub> = 100 °C	ID	6.6	А
Pulsed Drain Current <sup>a</sup>			I <sub>DM</sub>	21	
Linear Derating Factor				0.91	W/°C
Single Pulse Avalanche Energy <sup>b</sup>			E <sub>AS</sub>	103	mJ
Maximum Power Dissipation			PD	114	W
Operating Junction and Storage Temperature	Range		T <sub>J</sub> , T <sub>stg</sub>	-55 to +150	°C
Drain-Source Voltage Slope	$V_{DS} = 0$	V to 80 % V <sub>DS</sub>	d\//dt	70	1//20
Reverse Diode dV/dt <sup>d</sup>	·		dV/dt	27	V/ns
Soldering Recommendations (Peak Temperatu	ıre) <sup>c</sup> f	or 10 s		300	°C

#### Notes

a. Repetitive rating; pulse width limited by maximum junction temperature.

b.  $V_{DD}$  = 50 V, starting T<sub>J</sub> = 25 °C, L = 28.2 mH, R<sub>g</sub> = 25  $\Omega$ , I<sub>AS</sub> = 2.7 A.

c. 1.6 mm from case.

d.  $I_{SD} \leq I_D$ , dl/dt = 100 A/µs, starting  $T_J$  = 25 °C.

THERMAL RESISTANCE RATI	NGS			
PARAMETER	SYMBOL	TYP.	MAX.	UNIT
Maximum Junction-to-Ambient	R <sub>thJA</sub>	-	62	°C/W
Maximum Junction-to-Case (Drain)	R <sub>thJC</sub>	-	1.1	0/10

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PARAMETER	SYMBOL	TES	T CONDITIONS	MIN.	TYP.	MAX.	UNIT
Static		•		•		•	
Drain-Source Breakdown Voltage	V <sub>DS</sub>	V <sub>GS</sub> :	= 0 V, I <sub>D</sub> = 250 μΑ	500	-	-	V
V <sub>DS</sub> Temperature Coefficient	$\Delta V_{DS}/T_{J}$	Referenc	e to 25 °C, I <sub>D</sub> = 1 mA	-	0.60	-	V/°C
Gate-Source Threshold Voltage (N)	V <sub>GS(th)</sub>	V <sub>DS</sub> =	= V <sub>GS</sub> , I <sub>D</sub> = 250 μΑ	2.0	-	4.0	V
			V <sub>GS</sub> = ± 20 V	-	-	± 100	nA
Gate-Source Leakage	I <sub>GSS</sub>		V <sub>GS</sub> = ± 30 V	-	-	± 1	μA
Zaus Osta Valta na Dusia Ormant		V <sub>DS</sub> =	= 500 V, V <sub>GS</sub> = 0 V	-	-	1	
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	V <sub>DS</sub> = 400 \	/, V <sub>GS</sub> = 0 V, T <sub>J</sub> = 125 °C	-	-	10	μA
Drain-Source On-State Resistance	R <sub>DS(on)</sub>	$V_{GS} = 10 V$	I <sub>D</sub> = 6 A	-	0.330	0.380	Ω
Forward Transconductance		V <sub>DS</sub>	s = 30 V, I <sub>D</sub> = 6 A	-	3.1	-	S
Dynamic				•			
Input Capacitance	C <sub>iss</sub>		V <sub>GS</sub> = 0 V,		886	-	-
Output Capacitance	C <sub>oss</sub>	$V_{GS} = 0 V,$ $V_{DS} = 100 V,$		-	52	-	
Reverse Transfer Capacitance	C <sub>rss</sub>		f = 1 MHz	-	6	-	
Effective Output Capacitance, Energy Related <sup>a</sup>	C <sub>o(er)</sub>			-	45	-	pF
Effective Output Capacitance, Time Related <sup>b</sup>	C <sub>o(tr)</sub>	- V <sub>DS</sub> = 0 V	/ to 400 V, V <sub>GS</sub> = 0 V	-	131	-	
Total Gate Charge	Qg			-	25	50	
Gate-Source Charge	Q <sub>gs</sub>	V <sub>GS</sub> = 10 V	I <sub>D</sub> = 6 A, V <sub>DS</sub> = 400 V	-	6	-	nC
Gate-Drain Charge	Q <sub>gd</sub>			-	10	-	
Turn-On Delay Time	t <sub>d(on)</sub>			-	13	26	
Rise Time	t <sub>r</sub>	$V_{DD} = 400 \text{ V}, \text{ I}_{D} = 6 \text{ A}, \\ V_{GS} = 10 \text{ V}, \text{ R}_{g} = 9.1 \Omega$		-	16	32	ns
Turn-Off Delay Time	t <sub>d(off)</sub>			-	29	58	
Fall Time	t <sub>f</sub>			-	12	24	
Gate Input Resistance	Rg	f = 1 MHz, open drain		-	0.92	-	Ω
Drain-Source Body Diode Characteristic	s			•			
Continuous Source-Drain Diode Current	I <sub>S</sub>	MOSFET symbol showing the		-	-	10.5	
Pulsed Diode Forward Current	I <sub>SM</sub>	integral revers p - n junction		-	-	21	A
Diode Forward Voltage	V <sub>SD</sub>	T <sub>J</sub> = 25 °C	C, I <sub>S</sub> = 7.5 A, V <sub>GS</sub> = 0 V	-	-	1.2	V
Reverse Recovery Time	t <sub>rr</sub>			-	244	-	ns
Reverse Recovery Charge	Q <sub>rr</sub>		$T_J = 25 \text{ °C}, I_F = I_S = 6 \text{ A},$		2.5	-	μC
Reverse Recovery Current	I <sub>RRM</sub>	ai/dt =	100 A/µs, V <sub>R</sub> = 25 V	-	19	-	A

Notes

a.  $C_{oss(er)}$  is a fixed capacitance that gives the same energy as  $C_{oss}$  while  $V_{DS}$  is rising from 0 % to 80 %  $V_{DSS}$ . b.  $C_{oss(tr)}$  is a fixed capacitance that gives the same charging time as  $C_{oss}$  while  $V_{DS}$  is rising from 0 % to 80 %  $V_{DSS}$ .



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## TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)

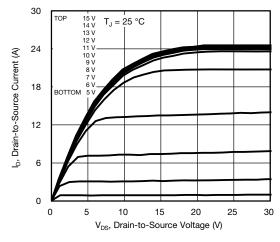


Fig. 1 - Typical Output Characteristics

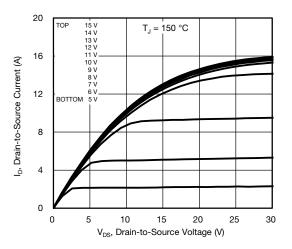


Fig. 2 - Typical Output Characteristics

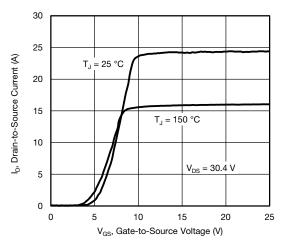


Fig. 3 - Typical Transfer Characteristics

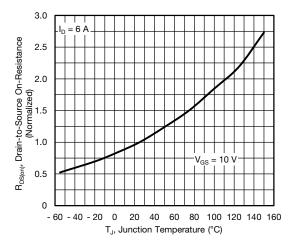


Fig. 4 - Normalized On-Resistance vs. Temperature

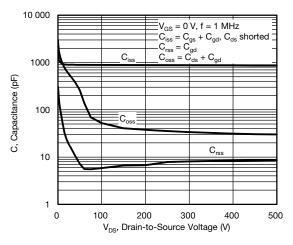


Fig. 5 - Typical Capacitance vs. Drain-to-Source Voltage

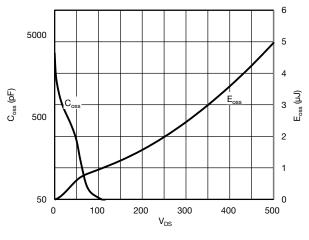


Fig. 6 -  $C_{\text{oss}}$  and  $E_{\text{oss}}$  vs.  $V_{\text{DS}}$ 

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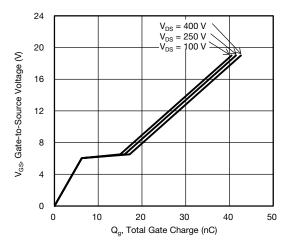


Fig. 7 - Typical Gate Charge vs. Gate-to-Source Voltage

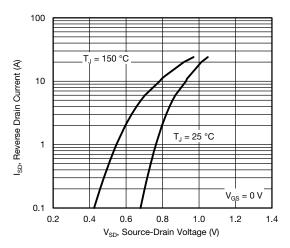


Fig. 8 - Typical Source-Drain Diode Forward Voltage

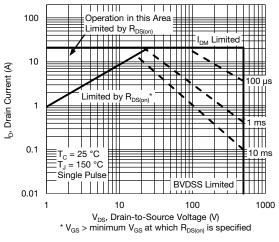


Fig. 9 - Maximum Safe Operating Area

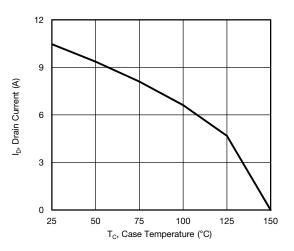


Fig. 10 - Maximum Drain Current vs. Case Temperature

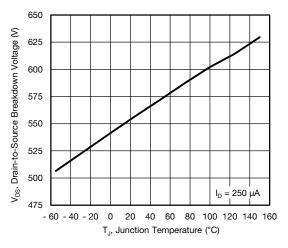


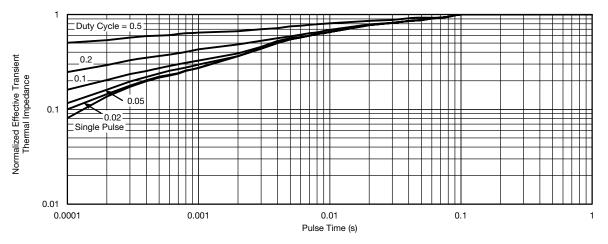
Fig. 11 - Temperature vs. Drain-to-Source Voltage

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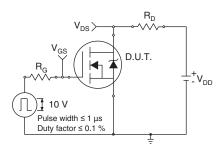


Fig. 13 - Switching Time Test Circuit

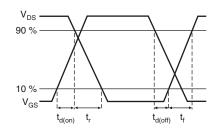


Fig. 14 - Switching Time Waveforms

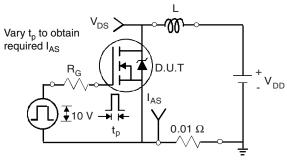


Fig. 15 - Unclamped Inductive Test Circuit

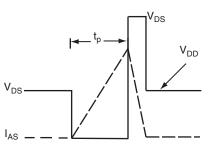


Fig. 16 - Unclamped Inductive Waveforms

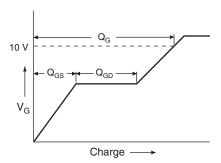


Fig. 17 - Basic Gate Charge Waveform

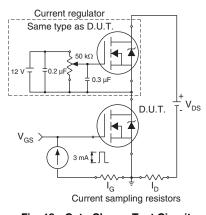


Fig. 18 - Gate Charge Test Circuit

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### Peak Diode Recovery dV/dt Test Circuit

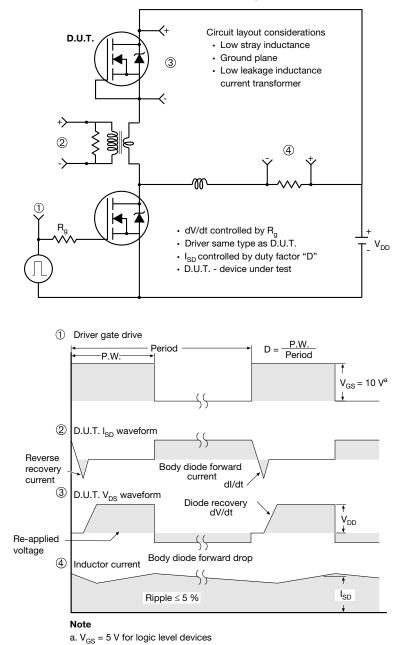


Fig. 19 - For N-Channel

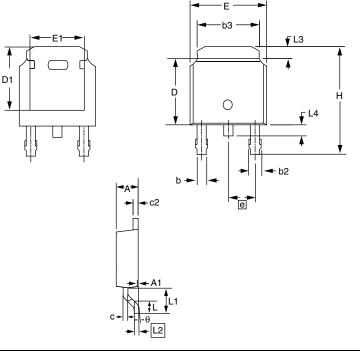
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# **Package Information**

**Vishay Siliconix** 

## **TO-252AA (HIGH VOLTAGE)**



DIM.	MILLI	METERS	INCHES	
	MIN.	MAX.	MIN.	MAX.
E	6.40	6.73	0.252	0.265
L	1.40	1.77	0.055	0.070
L1	2.74	2.743 REF		B REF
L2	0.508	3 BSC	0.020 BSC	
L3	0.89	1.27	0.035	0.050
L4	0.64	1.01	0.025	0.040
D	6.00	6.22	0.236	0.245
Н	9.40	10.40	0.370	0.409
b	0.64	0.88	0.025	0.035
b2	0.77	1.14	0.030	0.045
b3	5.21	5.46	0.205	0.215
е	2.286	5 BSC	0.090 BSC	
А	2.20	2.38	0.087	0.094
A1	0.00	0.13	0.000	0.005
С	0.45	0.60	0.018	0.024
c2	0.45	0.58	0.018	0.023
D1	5.30	-	0.209	-
E1	4.40	-	0.173	-
θ	0'	10'	0'	10'

Notes

1. Package body sizes exclude mold flash, protrusion or gate burrs. Mold flash, protrusion or gate burrs shall not exceed 0.10 mm per side.

2. Package body sizes determined at the outermost extremes of the plastic body exclusive of mold flash, gate burrs and interlead flash, but including any mismatch between the top and bottom of the plastic body.

3. The package top may be smaller than the package bottom.

4. Dimension "b" does not include dambar protrusion. Allowable dambar protrusion shall be 0.10 mm total in excess of "b" dimension at maximum material condition. The dambar cannot be located on the lower radius of the foot.



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## **RECOMMENDED MINIMUM PADS FOR DPAK (TO-252)**



Recommended Minimum Pads Dimensions in Inches/(mm)

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